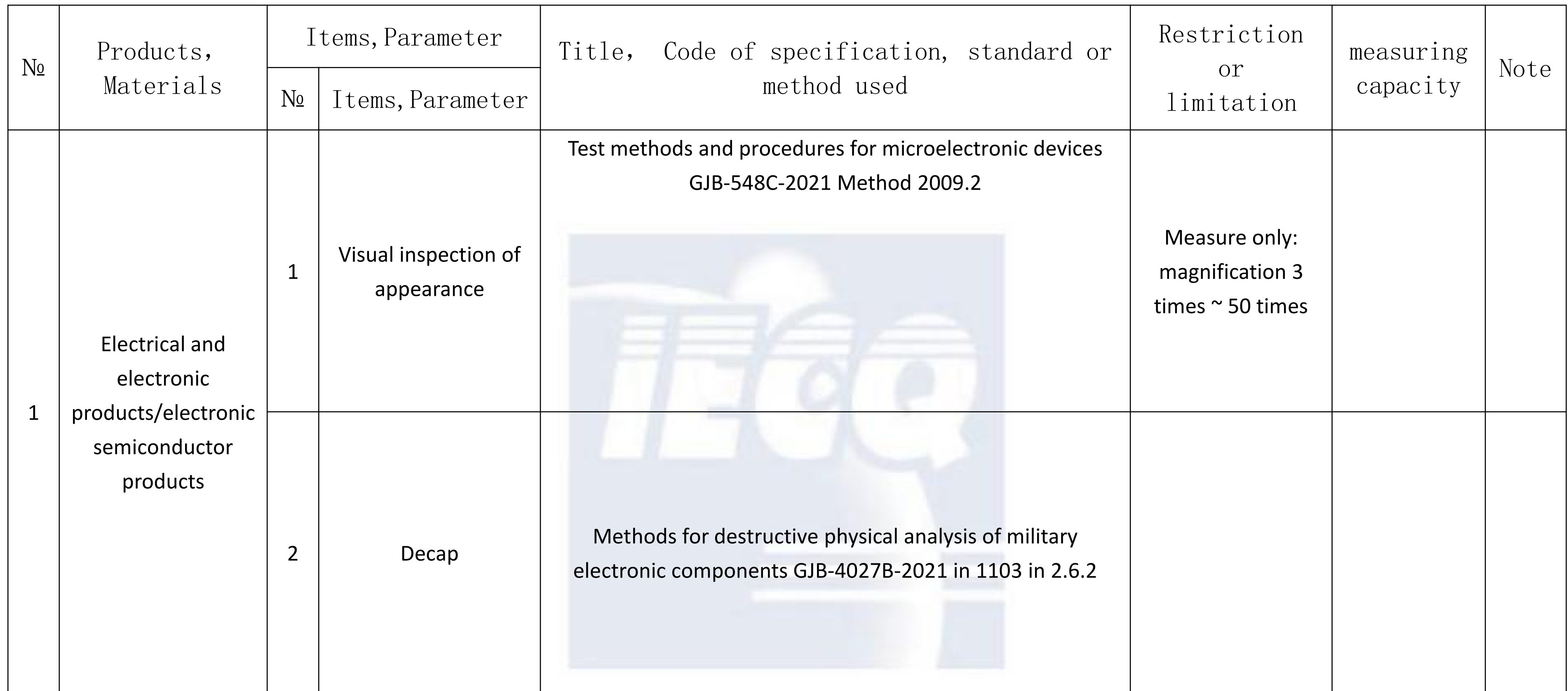
附表 3-2:　　　　　　　　　　批准证书附件

Lab: Juyue Inspection Technology Co., Ltd　　　　　Add: Room 101, Building 2, No. 1388 Zhangdong Road, Shanghai

№	Products, Materials	Items, Parameter		Title, Code of specification, standard or method used	Restriction or limitation	measuring capacity	Note
		№	Items, Parameter				
1	Electrical and electronic products/electronic semiconductor products	1	Visual inspection of appearance	Test methods and procedures for microelectronic devices GJB-548C-2021 Method 2009.2	Measure only: magnification 3 times ~ 50 times		
		2	Decap	Methods for destructive physical analysis of military electronic components GJB-4027B-2021 in 1103 in 2.6.2			



		3	SEM Inspection	Test methods and procedures for microelectronic devices GJB-548C-2021 Method 2018.2		Resolution: 1nm The maximum size of the plane can be moved: X/Y: 50*50mm, Z: 1.5_30mm	
		4	Delayer	Test Methods and Procedures for Microelectronic Devices GJB-548C-2021 Method 5003 in 3.3.3		Sample size no exceed 8 inches	
		5	IV CURVE	Test methods and procedures for microelectronic devices GJB-548C-2021 Method 5003 in 3.2.3.3.2.4		Range: ±9v 500mA resolution 2uA	

		6	InGaAs/OBIRCH	Test methods and procedures for microelectronic devices GJB-548C-2021 Method 5003 in 3.4(d)		Wavelength: 1300nm, detection voltage range: 0~20v, detection current capacity: 0-100mA	
		7	Cross-section Polish	Test methods and procedures for microelectronic devices GJB-548C-2021 method 5003 in 3.3.2			
		8	Probe Test	Test Methods and Procedures for Microelectronic Devices GJB-548C-2021 Method 5003 in 3.2.12			

		9	EDS Analysis	Test methods and procedures for microelectronic devices GJB-548C-2021 Method 5003 in 3.4.e		Plane 1um, depth 2um	